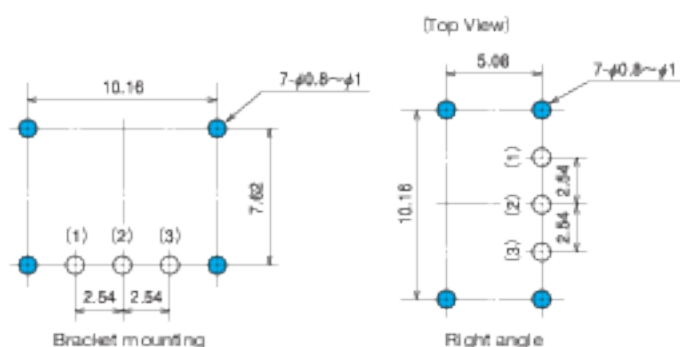
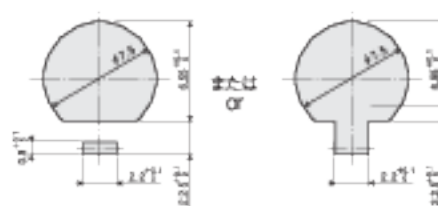


MRP**■Circuit Characteristics**

Operating direction	Connecting terminal	Step angle						
		0	18°	36°	324°	342°	360°	
Clockwise	2-1	ON	[Pulse waveform]					
		OFF	[Pulse waveform]					
Counterclockwise	2-3	ON	[Pulse waveform]					
		OFF	[Pulse waveform]					
360° Endless : 20±2 pulses								

■PC Hole Layouts**■Panel Cut-Out Dimensions**

Panel thickness : 2 mm max.

**■Handling Precautions (MRP & DRS series)****1. Soldering Specifications****(1) Manual Soldering**

Device : Soldering iron
270°C, Max.; 3 seconds, Max.

(2) Auto Soldering

Device: Jet wave type or dip type
260±5°C; 5 seconds, Max.

• Pre-heating should be done at temperatures of 100°C or below and within 30 sec.

(3)When soldering two or more terminals to the common land, use the solder resist to solder them independently.

2. Flux Cleaning

- (1) For the solvent, use the fluorine-based or alcohol-based solvent.
Solvent: Fluorine or Alcohol type
- (2) Since the **MRP** Series products are not waterproof-structured, if the PC board is to be cleaned, clean the soldering surface of substrate with a brush so that the switch is not exposed to the cleaning solution.

3. Mounting of Switch

- (1) Do not apply a load exceeding 29.4 N · cm to the fixing screws.
- (2) Do not bend the terminals before mounting the switch on the PC board.
- (3) After mounting the switch, do not place the device in such a way that the device weight will be applied on the knob, etc. of the switch.
- (4) Do not apply a load exceeding 16.7 N to the knob.